

MAC3030-8



Description

Designed primarily for full-wave AC control applications, such as light dimmers, motor controls, heating controls and power supplies; or wherever full-wave silicon gate controlled solid-state devices are needed. Triac type thyristors switch from a blocking to a conducting state for either polarity of applied main terminal voltage with positive or negative gate triggering.

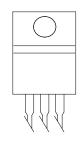
Features

- Blocking Voltage to 250 Volts
- All Diffused and Glass Passivated Junctions for Greater Parameter Uniformity and Stability
- Small, Rugged, Thermowatt Construction for Low Thermal Resistance, High Heat Dissipation and Durability
- Gate Triggering Guaranteed in Four Modes (Quadrants)
- Pb–Free Packages are Available

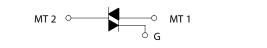
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Pin Out





Functional Diagram



Additional Information







Samples



Maximum Ratings $(T_1 = 25^{\circ}C \text{ unless otherwise noted})$

Rating	Symbol	Value	Unit
Peak Repetitive Off–State Voltage (Note 1) (– 40 to 1125°C, Sine Wave, 50 to 60 Hz, Gate Open)	V _{drm} , V _{rrm}	250	V
On-State RMS Current (T _c = +70°C) Full Cycle Sine Wave, 50 to 60 Hz	I _{T (RMS)}	8.0	А
Peak Non-Repetitive Surge Current (One Full Cycle Sine Wave, 60 Hz, $T_c = +25^{\circ}C$) Preceded and followed by rated current	I _{TSM}	80	А
Circuit Fusing Consideration (t = 8.3 ms)	l²t	26	A ² sec
Peak Gate Current, (TC = $+70^{\circ}$ C, Pulse Width = 10μ s)	I _{GM}	2.0	А
Peak Gate Power (T _c = +70°C, Pulse Width = 10 μ s)	P _{GM}	20	W
Average Gate Power ($T_c = +70^{\circ}$ C, t = 8.3 ms)	P _{G (AV)}	0.35	W
Operating Junction Temperature Range	TJ	-40 to +125	°C
Storage Temperature Range	T _{stq}	-40 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. V_{DBM} and V_{RBM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

Thermal Characteristics

Rating		Symbol	Value	Unit
Thermal Resistance,	Junction-to-Case (AC) Junction-to-Ambient	R _{ejc} R _{eja}	2.0 62.5	°C/W
Maximum Lead Temperature for Soldering Purpose 10 seconds	TL	260	°C	

Electrical Characteristics • **OFF** (T₁ = 25°C unless otherwise noted ; Electricals apply in both directions)

Characteristic		Symbol	Min	Тур	Мах	Unit
Peak Repetitive Blocking Current	T ₁ = 25°C	I _{DRM} ,	-	-	1.0	~^
$(V_{D} = V_{DRM} = V_{RRM}; Gate Open)$	T _J = 125°C	I _{RRM}	-	-	2.0	mA

Electrical Characteristics · **ON** ($T_1 = 25^{\circ}$ C unless otherwise noted; Electricals apply in both directions)

Characteristic		Symbol	Min	Тур	Max	Unit
Peak On–State Voltage ($I_{TM} = \pm 11$ A Peak, Pulse Width ≤ 2 ms, Duty Cycle $\leq 2\%$)		V _{TM}	-	1.2	1.65	V
	MT2(+), G(+)		-	12	50	
Gate Trigger Current	MT2(+), G(-)		-	12	50	mA
(Continuous dc) ($V_D = 12 V, R_L = 100 Ohms$)	MT2(-), G(-)	GT	-	20	50	ma
	MT2(-), G(+)		-	35	75	
	MT2(+), G(+)		-	0.9	2.0	
Gate Trigger Voltage	MT2(+), G(-)		-	0.9	2.0	
(Continuous dc) ($V_p = 12 V, R_1 = 100 \Omega$)	MT2(-), G(-)	V _{GT}	_	1.1	2.0	V
	MT2(-), G(+)		_	1.4	2.5	
Gate Non–Trigger Voltage (Continuous DC), (V $_{\rm D}$ = 12 V, T $_{\rm C}$ = 110°C, R $_{\rm L}$ = 100 Ω) All Four Quadrants		V _{gd}	0.2	-	_	V
Holding Current (V _D = 12 V _{dc'} Gate Open, Initiating Current = \pm 200 mA))		I _H	-	6.0	50	mA
Turn-On Time (Rated $V_{_{DRM'}}$ I $_{TM}$ = 11 A) (I $_{_{GT}}$ = 120 mA, Rise Time = 0.1 s, Pulse Width = 2 s)		t _{gt}	_	1.5	-	μs

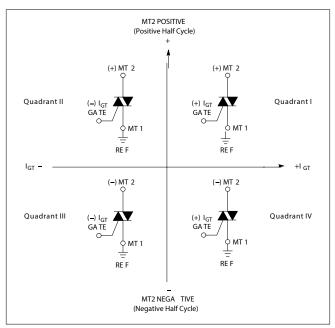




Dynamic Characteristics						
Characteristic	Symbol	Min	Тур	Мах	Unit	
Critical Rate of Rise of Commutation Voltage (V _D = Rated V _{DRM} , I _{TM} = 14 A, Commutating di/dt = 5.0 A/ms, Gate Unenergized, T _C = 70°C)	(di/dt)c	-	5.0	-	A/ms	
Critical Rate of Rise of Off-State Voltage ($V_D = Rated V_{DRM'}$ Exponential Waveform, Gate Open, $T_c = \pm 70^{\circ}C$)	dv/dt	-	100	-	V/µs	

Voltage Current Characteristic of SCR

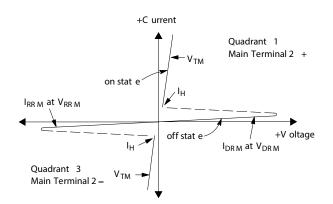
Symbol	Parameter
V _{DRM}	Peak Repetitive Forward Off State Voltage
I	Peak Forward Blocking Current
V _{RRM}	Peak Repetitive Reverse Off State Voltage
I	Peak Reverse Blocking Current
V _{TM}	Maximum On State Voltage
I _H	Holding Current



Quadrant Definitions for a Triac

All polarities are referenced to MT1.

With in-phase signals (using standard AC lines) quadrants I and III are used





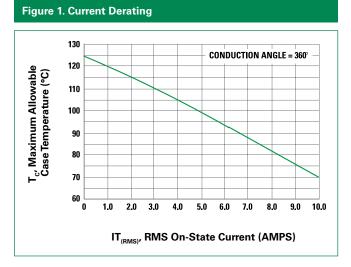


Figure 3. Maximum On–State Characteristics

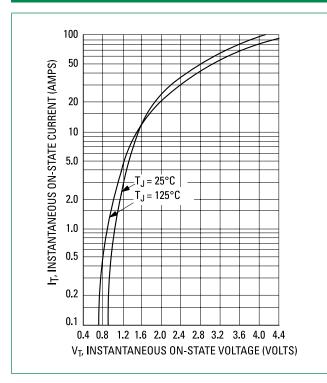


Figure 2. Power Dissipation

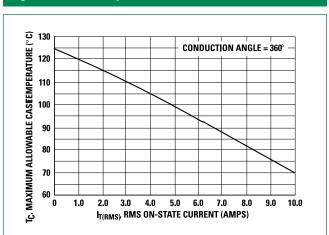


Figure 4. Maximum Non-Repetitive Surge Current

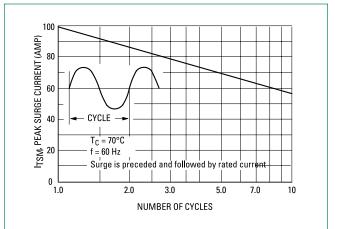


Figure 5. Typical Gate Trigger Voltage

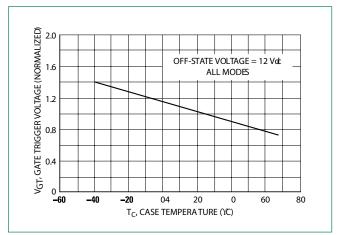




Figure 6. Typical Gate Trigger Current

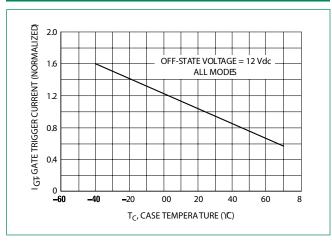


Figure 7. Typical Holding Current

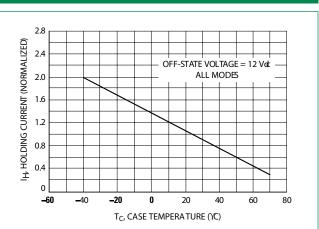
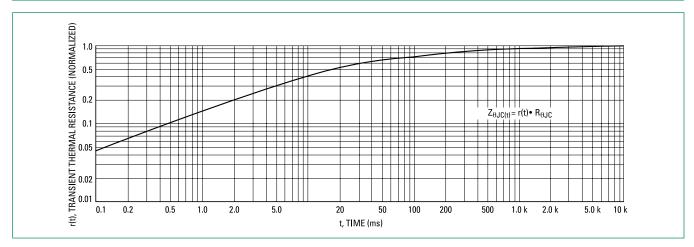


Figure 8. Thermal Response

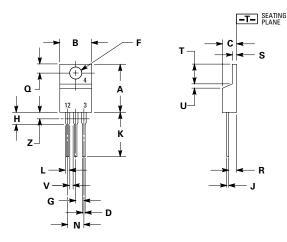




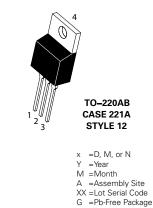
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Dimensions



Part Marking System





Dim	Inc	Inches		neters
Dim	Min	Мах	Min	Мах
Α	0.590	0.620	14.99	15.75
В	0.380	0.420	9.65	10.67
С	0.178	0.188	4.52	4.78
D	0.025	0.035	0.64	0.89
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.41	2.67
Н	0.110	0.130	2.79	3.30
J	0.018	0.024	0.46	0.61
К	0.540	0.575	13.72	14.61
L	0.060	0.075	1.52	1.91
Ν	0.195	0.205	4.95	5.21
٥	0.105	0.115	2.67	2.92
R	0.085	0.095	2.16	2.41
S	0.045	0.060	1.14	1.52
т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
v	0.045		1.15	
Z		0.080		2.04

Pin Assignment			
1	Main Terminal 1		
2	Main Terminal 2		
3	Gate		
4	No Connection		

Ordering Information		
Device	Package	Shipping
MAC3030-8	TO-220AB	500 Units/ Box
MAC3030-8G	TO-220AB (Pb-Free)	500 Units/ Box

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

2. CONTROLLING DIMENSION: INCH.

3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

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